TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

PCN# 20150821000
Qualification of ASESH as Additional Assembly Site for Select TSSOP Package Devices
Change Notification / Sample Request

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

PCN# 20150821000
Attachment: 1

Products Affected:

According to our records, there are the affected device(s) that you have purchased within the past twenty-four (24) months. Technical details of this Product Change follow on the next page(s).

PCN Number:	20150821000	**PCN Date:**	08/24/2015
Title:	Qualification of ASESH as Additional Assembly Site for Select TSSOP Package Devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	11/24/2015	**Estimated Sample Availability:**	Date Provided at Sample request

Change Type:

☒	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

Description of Change:

Qualification of ASESH as Additional Assembly Site for Select TSSOP Package Devices. Assembly differences are shown in the following table:

Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City
TI Malaysia	MLA	MY	Kuala Lumpur
ASESH	**ASH**	**CN**	**Shanghai**

Material Differences:

	TI Malaysia	**ASESH**
Mount Compound	4042500	EY1000063
Mold Compound	4206193	EN2000507

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA
ASESH	Assembly Site Origin (22L)	ASO: ASH

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
G4
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750
(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO:SHE (21L) CCO:USA
(22L) ASO:MLA (23L) ACO:MYS

ASSEMBLY SITE CODES: TI Malaysia =K, ASESH = A

Product Affected:

CDCV304PW	CDCV304PWG4	CDCV304PWR	CDCV304PWRG4

Qualification Report

CDCV304PW: Qualification of alternative Assembly Site (ASESH)

Product Attributes

Attributes	Qual Device: CDCV304
Assembly Site	ASE SHANGHAI (ASESH)
Package Family	TSSOP
Flammability Rating	UL 94 V-0
Wafer Fab Site	ANAM (DONGBU)
Wafer Fab Process	33C10

- QBS: Qual By Similarity
- Qual Device CDCV304 is qualified at LEVEL1-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CDCV304
PC	PreCon Level 1	25C	1/280/0
AC	Autoclave 121C	96 Hours	1/80/0
TC	Temperature Cycle, -65/150C	500 Cycles	1/80/0
HTSL	High Temp Storage Bake 150C	1000 Hours	1/80/0
MQ	Manufacturability	(per mfg. Site specification)	Pass
ED	Electrical Characterization	Per Datasheet Parameters	1/Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com